

SOT8019-1 wafer level chip-scale package, 12 bumps; 1.36 x 1.86 x 0.60 mm

11 February 2022

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP12
Package type industry code	WLCSP12
Package style descriptive code	UC (uncased chip)
Package body material type	X (other)
Mounting method type	S (surface mount)
Number of package outline detail graphic references	0
Issue date	12-8-2020
Manufacturer package code	SOT8019

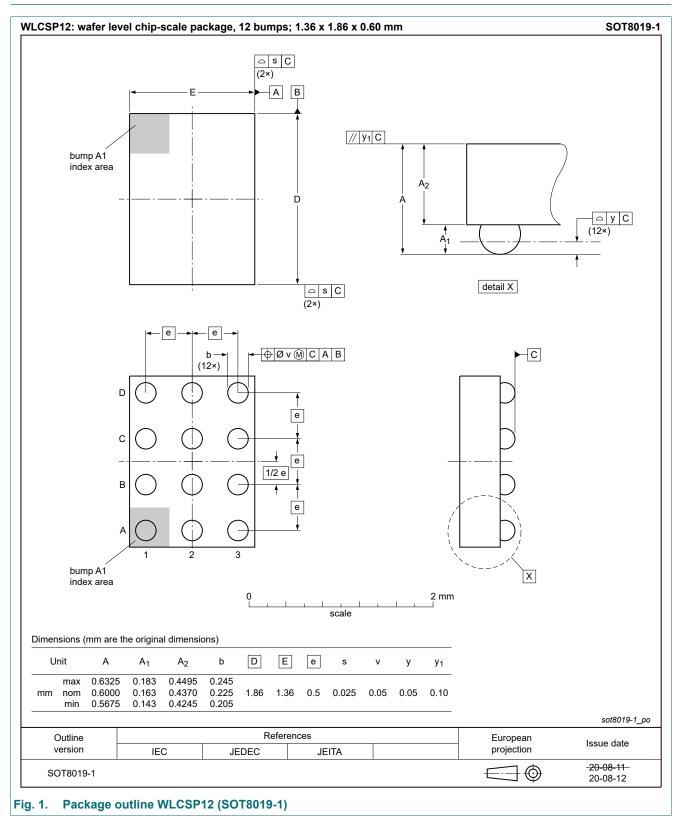
Table 1. Package summary

Symbol	Parameter	Min	Тур	Nom	Max	Unit
D	package length	-	-	1.86	-	mm
E	package width	-	-	1.36	-	mm
A	seated height	0.5675	-	0.6	0.6325	mm
A ₂	package height	0.425	-	0.437	0.449	mm
е	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	12	-	

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2. Package outline



Package information

3. Legal information

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